

L Number	Hits	Search Text	DB	Time stamp
1	136718	surface near3 (sponge or absorb\$3 or adsorb\$3 or pad or applicator)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/05 12:34
2	12734	((surface near3 (sponge or absorb\$3 or adsorb\$3 or pad or applicator)) and (electroplat\$410 or electrodeposit\$10 or electroly\$10 or electrochem\$10))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/05 12:25
3	12734	((surface near3 (sponge or absorb\$3 or adsorb\$3 or pad or applicator)) and (electroplat\$10 or electrodeposit\$10 or electroly\$10 or electrochem\$10))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/05 12:25
4	1673	((surface near3 (sponge or absorb\$3 or adsorb\$3 or pad or applicator)) and (electroplat\$10 or electrodeposit\$10 or electroly\$10 or electrochem\$10)) and ((remov\$3 or deplat\$3) near3 metal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/05 12:27
5	818	((surface near3 (sponge or absorb\$3 or adsorb\$3 or pad or applicator)) and (electroplat\$10 or electrodeposit\$10 or electroly\$10 or electrochem\$10)) and ((remov\$3 or deplat\$3) near3 metal)) and (voltage or potential or bias)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/05 12:30
6	1048	((surface near3 (sponge or absorb\$3 or adsorb\$3 or pad or applicator)) and (electroplat\$10 or electrodeposit\$10 or electroly\$10 or electrochem\$10)) and ((remov\$3 or deplat\$3) near3 metal)) and (voltage or potential or bias)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/05 12:30
7	663	((surface near3 (sponge or absorb\$3 or adsorb\$3 or pad or applicator)) and (electroplat\$10 or electrodeposit\$10 or electroly\$10 or electrochem\$10)) and ((remov\$3 or deplat\$3) near3 metal)) and (voltage or potential or bias)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/05 12:31
8	212	((surface near3 (sponge or absorb\$3 or adsorb\$3 or pad or applicator)) and (electroplat\$10 or electrodeposit\$10 or electroly\$10 or electrochem\$10)) and ((remov\$3 or deplat\$3) near3 metal)) and (voltage or potential or bias)) and semiconductor) and ((liquid or electrolyte or fluid or solution) near5 (sponge or absorb\$3 or adsorb\$3 or pad or applicator))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/05 12:34